

SOLIDWORKS GENERATED DRAWING, DON'T CHANGE BY HAND.

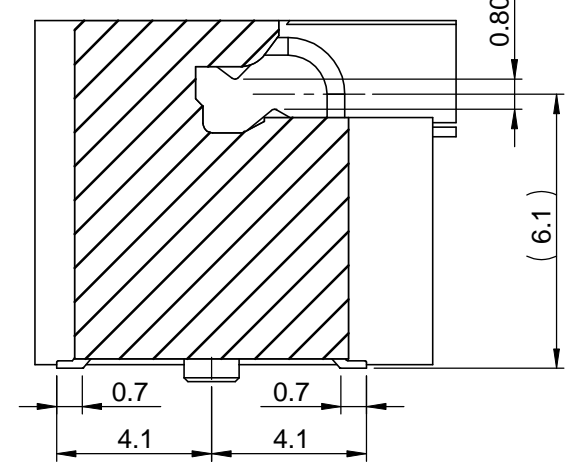
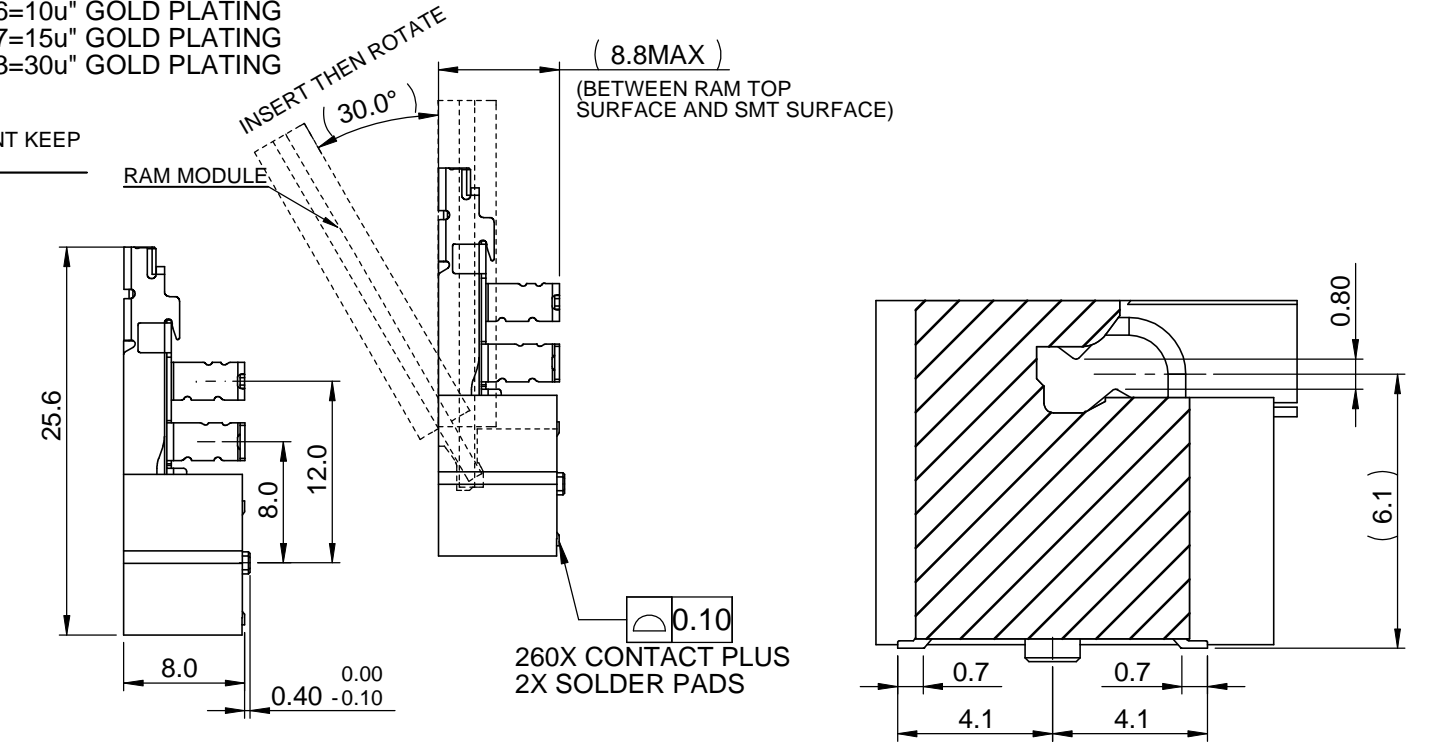
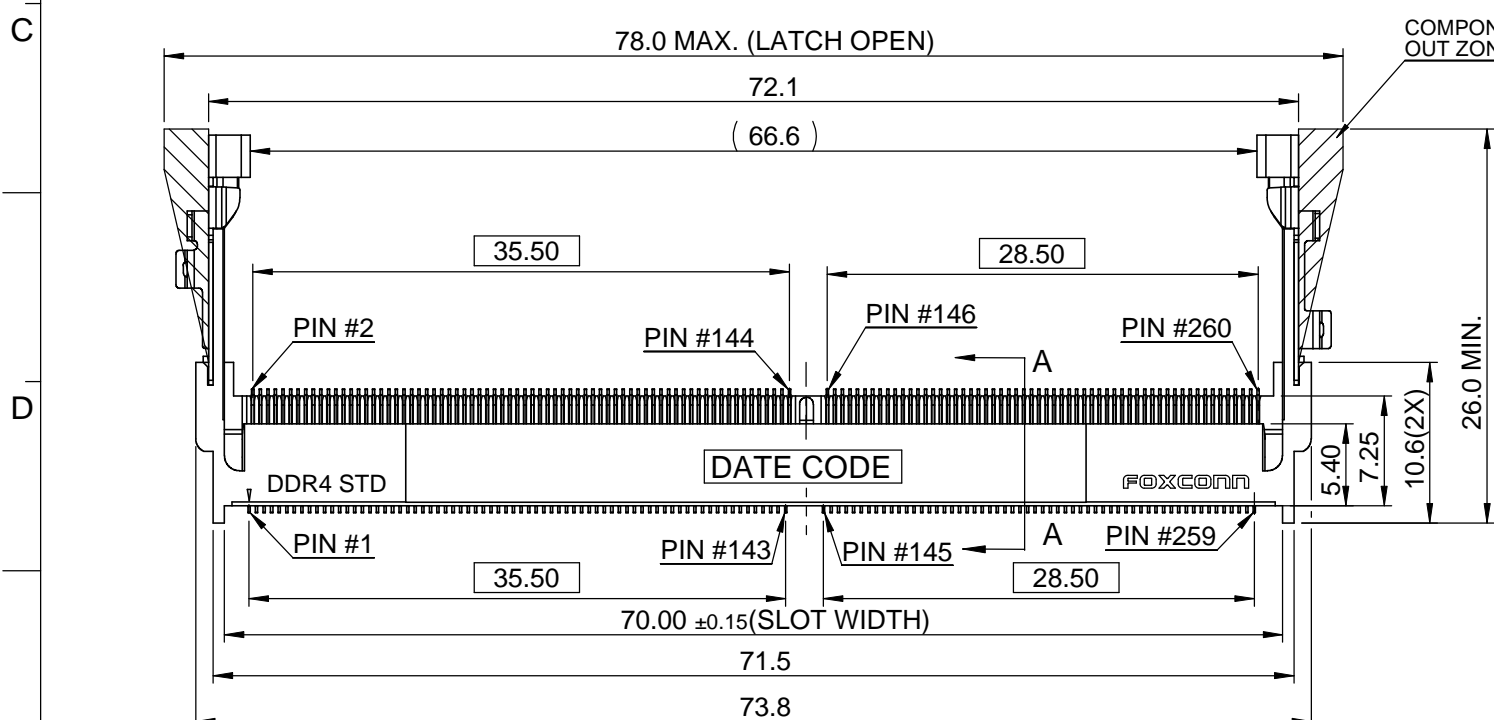
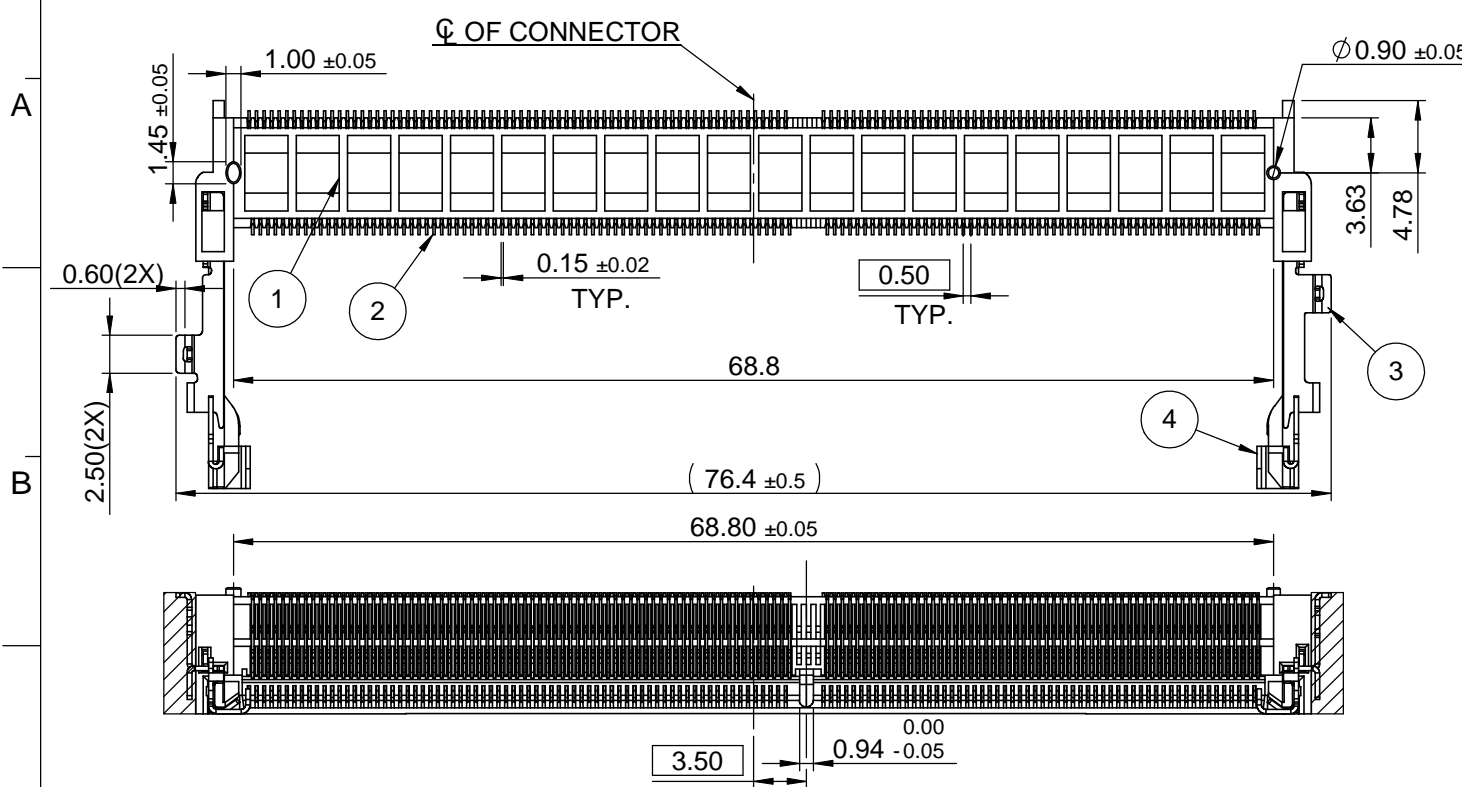
REV.	ECN. NO.	APPD.
A	BC-15-0028584	Bruce Wu
B	BC-16-0008757	Bruce Wu

- NOTES:
- ELECTRICAL CHARACTERISTICS:
    - CONTACT CURRENT RATING: 0.5 AMPERE MAX. PER PIN.
    - VOLTAGE RATING: 25V AC.
    - INSULATION RESISTANCE: 100 MEGAOHMS MIN. AT 500V DC.
    - DIELECTRIC WITHSTANDING VOLTAGE: 250V AC RMS AT 60Hz, FOR 1 MINUTE.
    - CONTACT RESISTANCE: 60 MILLIOHMS MAX. PER PIN INITIAL  
 $\Delta$  10 MILLIOHMS PER PIN AFTER FULL ENVIRONMENTAL TESTING.
  - MECHANICAL CHARACTERISTICS: DURABILITY: 60 MATING CYCLES.
  - OPERATION TEMPERATURE: -55 °C TO +85 °C.
  - RECOMMENDED PROCESS CONDITION: SMT, PEAK TEMPERATURE: 260 °C 10~20S.
  - PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAILS & AVAILABILITY.

DATE CODE: \* \* \* \* \*  
 YEAR MONTH LINE NO. DAY

MEMORY MODULE SOCKET  
 HORIZONTAL TYPE  
 SINGLE ROW  
 NO. OF POS.  
 A8=260 POS.  
 SMT  
 CONTACT AREA PLATING  
 1=GOLD FLASH  
 Y=5u" GOLD PLATING  
 6=10u" GOLD PLATING  
 7=15u" GOLD PLATING  
 3=30u" GOLD PLATING

A S A A8 2 \* - E 8 S B 0 - \* H  
 H=HALOGEN FREE & LEAD FREE  
 7=TAPE REEL  
 4=SOFT TRAY  
 0=EXTENSION CODE  
 B=NORMAL TYPE, BLACK COLOR  
 S=STANDARD  
 8=8.0MM HEIGHT  
 E=DDR SODIMM

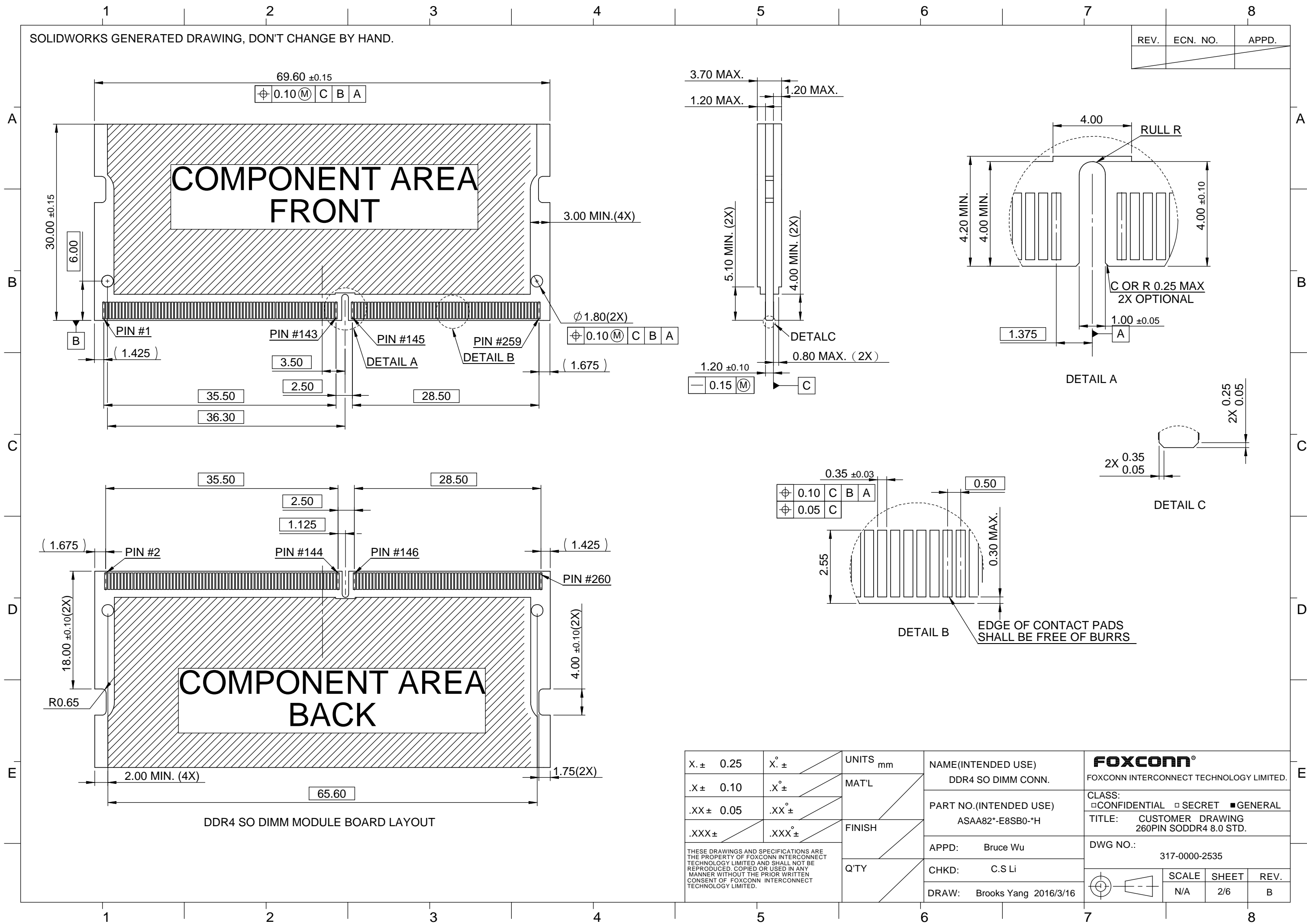


ITEM	DESCRIPTION	Q'TY	METERIAL	TREATMENT
4	METAL SPRING	2	STAINLESS STEEL	ULTRASONIC CLEANING
3	METAL PAD	2	STAINLESS STEEL	10u" NICKEL UNDER PLATING 100u" MATTE TIN PLATING OVER SOLDER PAD AREA.
2	CONTACT	260	PHOSPHOR BRONZE	50u" NICKEL UNDER PLATING GOLD FLASH OR 5u" OR 10u" AT CONTACT AREA; 90u" NICKEL UNDER PLATING 15u" OR 30u" GOLD PLATING AT CONTACT AREA; GOLD FLASH PLATING AT TAIL
1	HOUSING	1	LCP	UL94V-0, HALOGEN FREE, BLACK COLOR

X. ± 0.30	X° ±	UNITS mm	NAME (INTENDED USE) DDR4 SO DIMM CONN.	<b>FOXCONN®</b> FOXCONN INTERCONNECT TECHNOLOGY LIMITED. CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL TITLE: CUSTOMER DRAWING 260PIN SODDDR4 8.0 STD. DWG NO.: 317-0000-2535	
.X ± 0.25	.X° ±	MAT'L	PART NO. (INTENDED USE) ASAA82*-E8SB0-*H		
.XX ± 0.15	.XX° ±	FINISH	APPD: Bruce Wu		
.XXX ±	.XXX° ±	Q'TY	CHKD: C.S Li		
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.			DRAW: Brooks Yang 2016/3/16		
			SCALE	SHEET	REV.
			N/A	1/6	B

SOLIDWORKS GENERATED DRAWING, DON'T CHANGE BY HAND.

REV.	ECN. NO.	APPD.

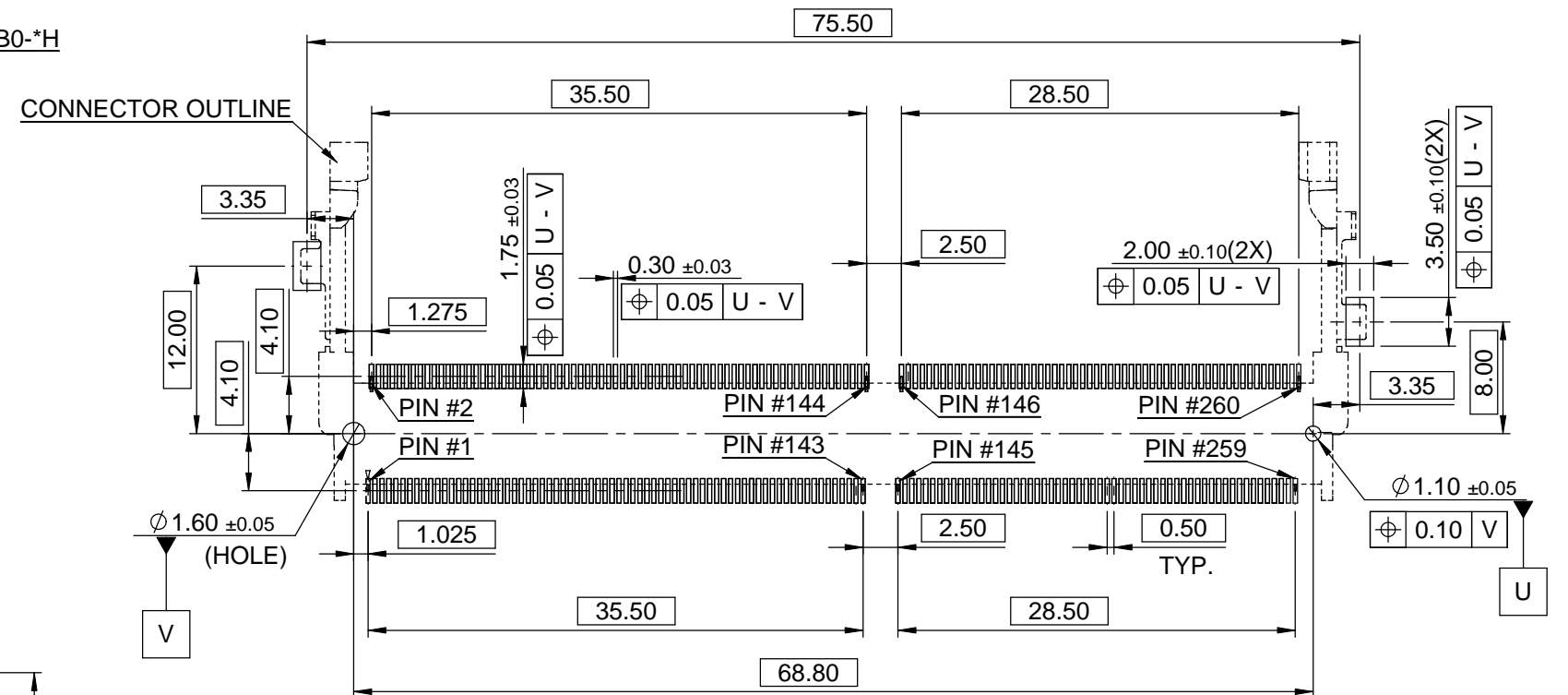
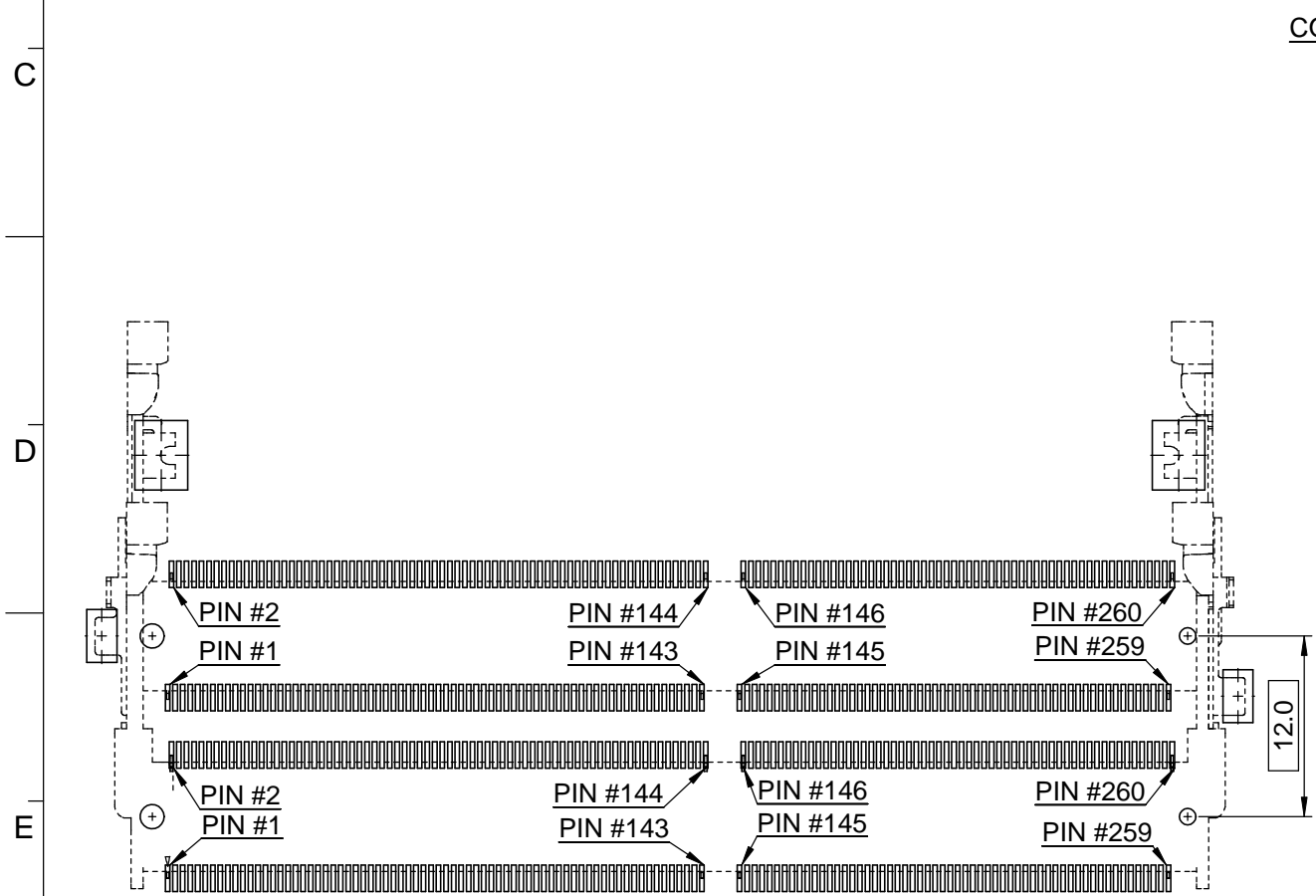
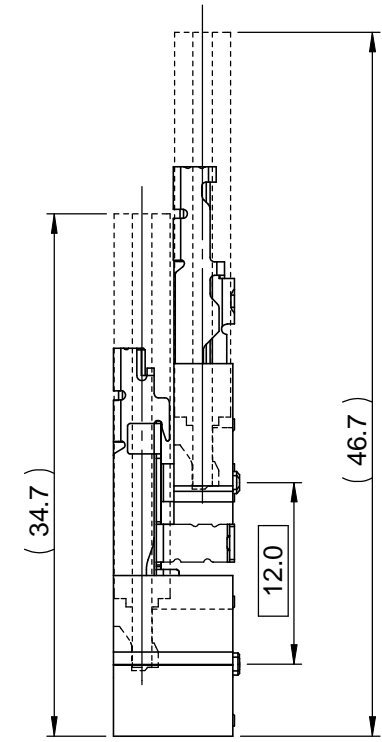
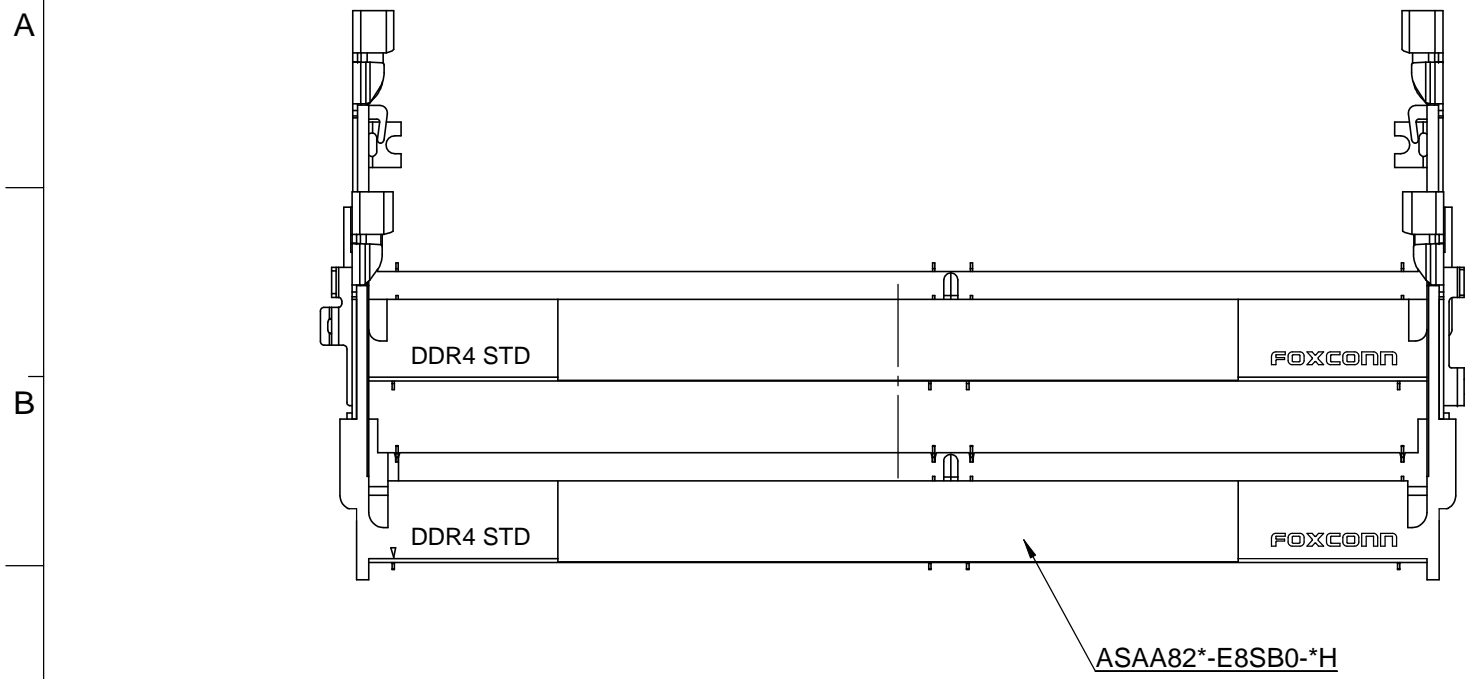


DDR4 SO DIMM MODULE BOARD LAYOUT

X. ± 0.25	X° ±	UNITS mm	NAME (INTENDED USE) DDR4 SO DIMM CONN.	<b>FOXCONN®</b> FOXCONN INTERCONNECT TECHNOLOGY LIMITED. CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL TITLE: CUSTOMER DRAWING 260PIN SODDDR4 8.0 STD.						
.X ± 0.10	.X° ±	MAT'L	PART NO. (INTENDED USE) ASAA82*-E8SB0-*H							
.XX ± 0.05	.XX° ±	FINISH	APPD: Bruce Wu	DWG NO.: 317-0000-2535						
.XXX ±	.XXX° ±	Q'TY	CHKD: C.S Li	<table border="1"> <thead> <tr> <th>SCALE</th> <th>SHEET</th> <th>REV.</th> </tr> </thead> <tbody> <tr> <td>N/A</td> <td>2/6</td> <td>B</td> </tr> </tbody> </table>	SCALE	SHEET	REV.	N/A	2/6	B
SCALE	SHEET	REV.								
N/A	2/6	B								
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.			DRAW: Brooks Yang 2016/3/16							

SOLIDWORKS GENERATED DRAWING, DON'T CHANGE BY HAND.

REV.	ECN. NO.	APPD.



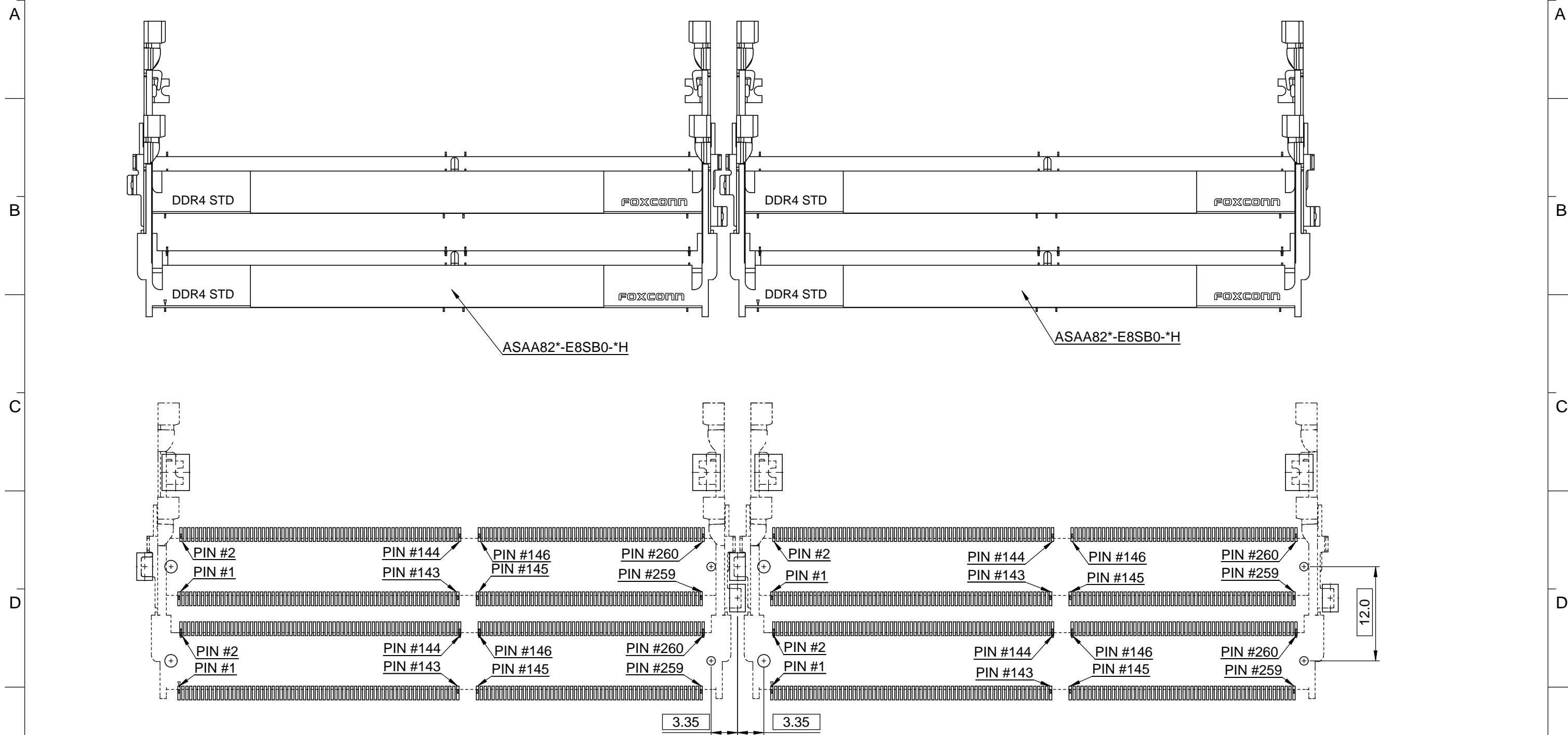
P.C.B. LAYOUT(STACKED ORIENTATION)

P.C.B. LAYOUT(RECOMMEND THICKNESS = 1.40MM)

X. ± 0.25	X° ±	UNITS mm	NAME(INTENDED USE)	<b>FOXCONN®</b> FOXCONN INTERCONNECT TECHNOLOGY LIMITED.	
.X ± 0.10	.X° ±		DDR4 SO DIMM CONN.		
.XX ± 0.05	.XX° ±	FINISH	PART NO.(INTENDED USE)	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL	
.XXX ±	.XXX° ±		ASAA82*-E8SB0-*H	TITLE: CUSTOMER DRAWING 260PIN SODDR4 8.0 STD.	
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.			APPD: Bruce Wu	DWG NO.:	
			CHKD: C.S Li	317-0000-2535	
			DRAW: Brooks Yang 2016/3/16		
			SCALE	SHEET	REV.
			N/A	3/6	B

SOLIDWORKS GENERATED DRAWING, DON'T CHANGE BY HAND.

REV.	ECN. NO.	APPD.

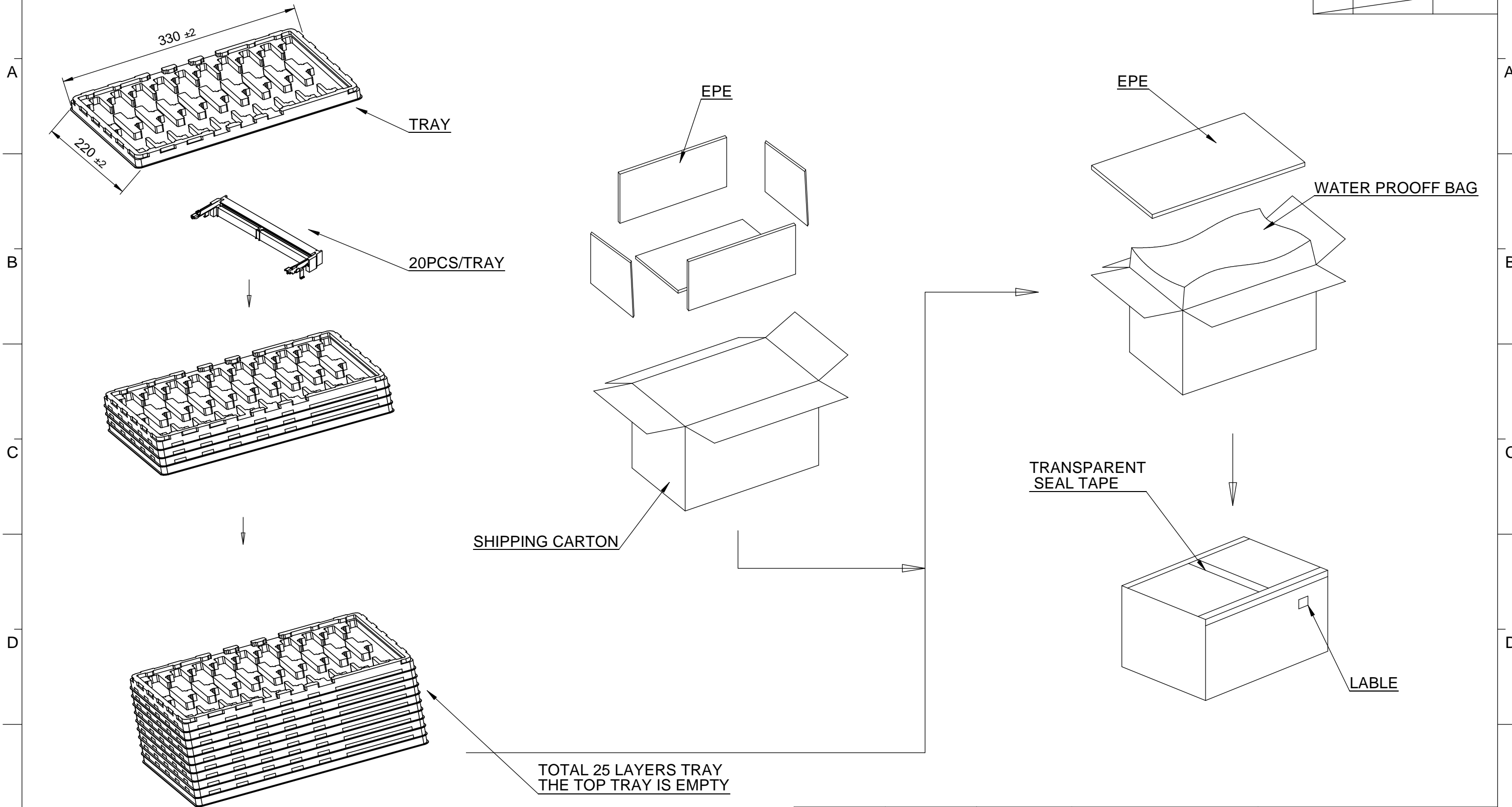


P.C.B. LAYOUT(DUAL COMPRESSED STACKED ORIENTATION)

X. ± 0.25	X° ±	UNITS mm	NAME(INTENDED USE) DDR4 SO DIMM CONN.	<b>FOXCONN®</b> FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X ± 0.10	.X° ±			
.XX ± 0.05	.XX° ±	FINISH	PART NO.(INTENDED USE) ASAA82*-E8SB0-*H	TITLE: CUSTOMER DRAWING 260PIN SODDDR4 8.0 STD.
.XXX ±	.XXX° ±		Q'TY	APPD: Bruce Wu
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.				CHKD: C.S Li
			DRAW: Brooks Yang 2016/3/16	

SOLIDWORKS GENERATED DRAWING, DON'T CHANGE BY HAND.

REV.	ECN. NO.	APPD.

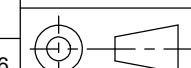


PACKING CAPACITY : 20 PCS/TRAY, 24 TRAYS/BOX,  
TOTAL 480 PCS/BOX.

TOTAL 25 LAYERS TRAY  
THE TOP TRAY IS EMPTY

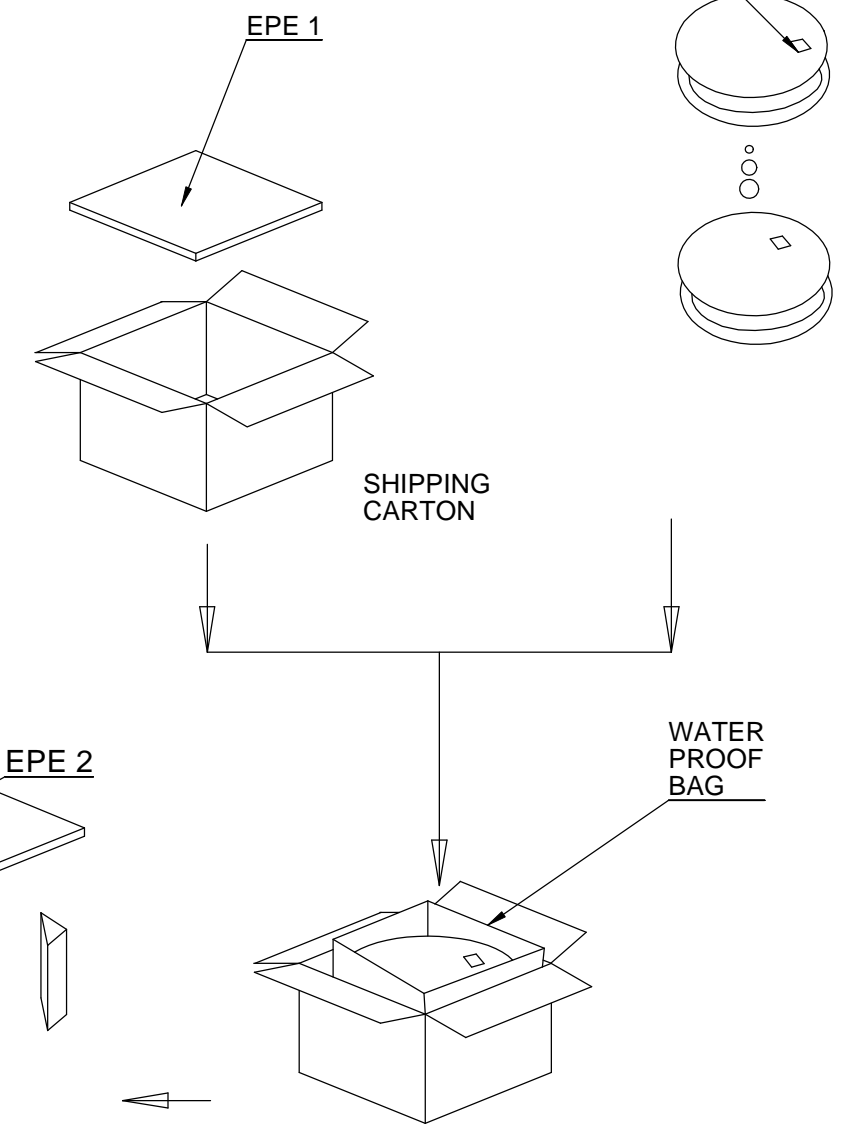
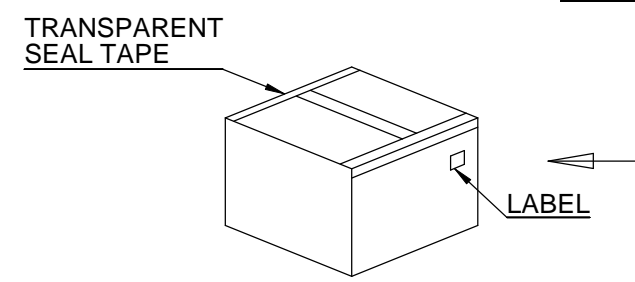
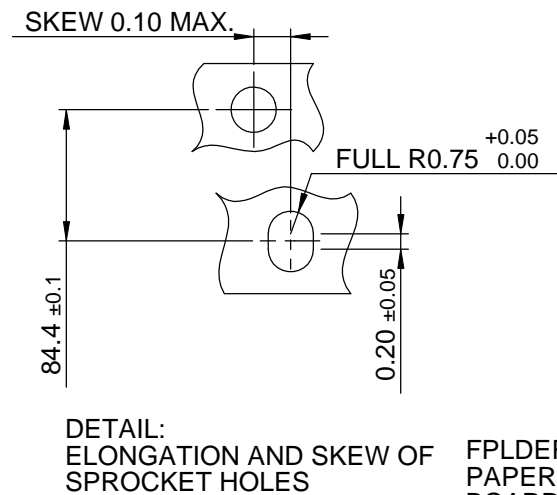
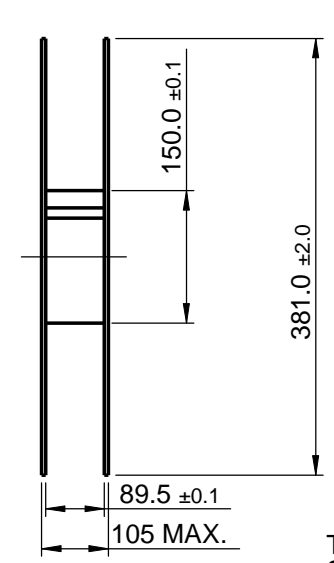
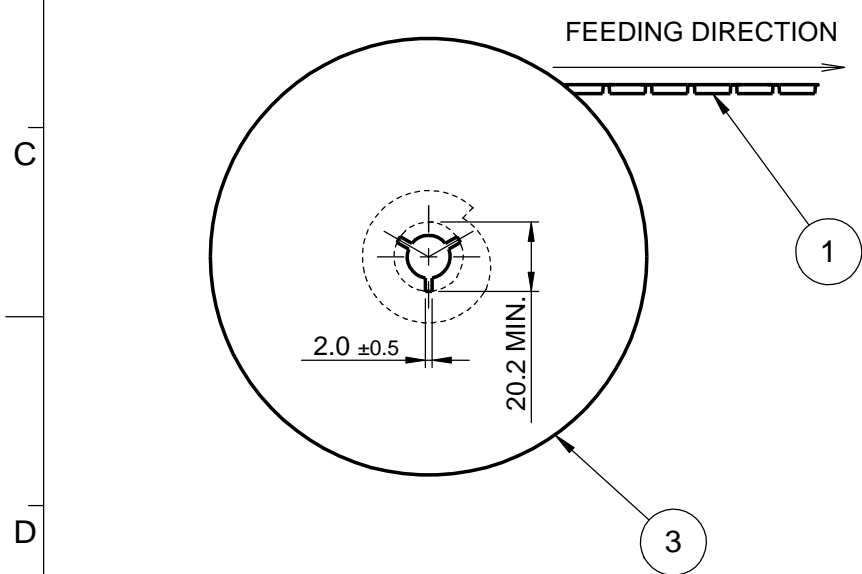
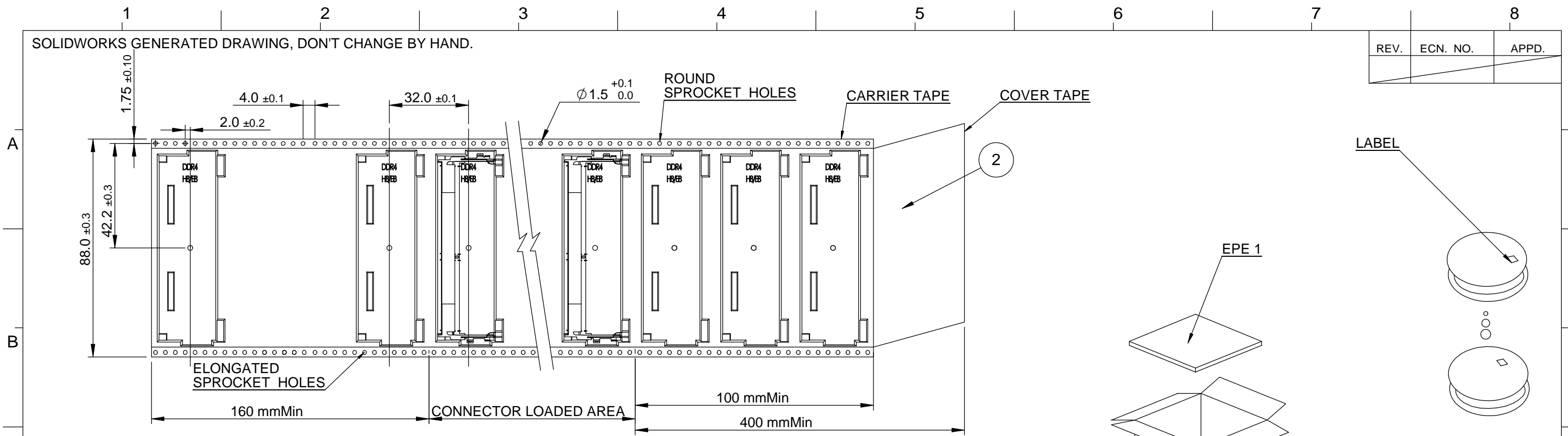
CONNECTOR P/N ASAA82\*-E8SB0-4H

X. ± 1.5	X° ±	UNITS mm	NAME (INTENDED USE)	<b>FOXCONN®</b> FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X ± 1.0	.X° ±		DDR4 SO DIMM CONN.	
.XX ± 0.2	.XX° ±	MAT'L	PART NO. (INTENDED USE)	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
.XXX ±	.XXX° ±		ASAA82*-E8SB0-*H	TITLE: CUSTOMER DRAWING 260PIN SODDR4 8.0 STD.
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.			FINISH	DWG NO.: 317-0000-2535
			Q'TY	APPD: Bruce Wu
			CHKD: C.S Li	SCALE SHEET REV. N/A 5/6 B
			DRAW: Brooks Yang 2016/3/16	



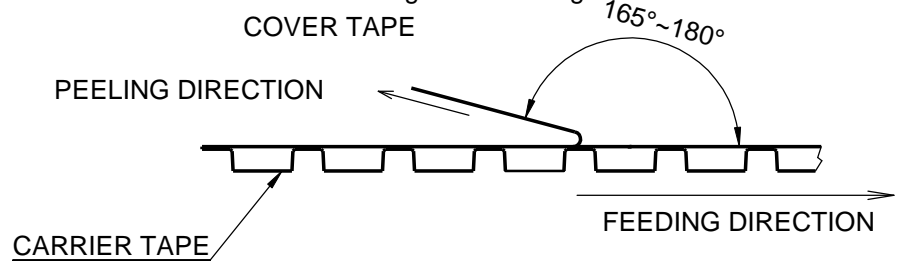
SOLIDWORKS GENERATED DRAWING, DON'T CHANGE BY HAND.

REV.	ECN. NO.	APPD.



NOTES:

- 10 POCKETS HOLE PITCH CUMULATIVE TOLERANCE ±0.20mm.
- COVER TAPE PEELING STRENGTH : 0.01 kgf MIN. 0.15 kgf MAX. AT 300mm/min.



3. PACKING CAPACITY : 260 PCS/REEL, 3 REELS/BOX, TOTAL 780 PCS/BOX.

3	REEL	POLYSTYRENE
2	COVER TAPE	POLYESTER
1	CARRIER TAPE	POLYSTYRENE
ITEM	DESCRIPTION	MATERIAL

X. ± 1.5	X° ±	UNITS mm	NAME (INTENDED USE) DDR4 SO DIMM CONN.	<b>FOXCONN®</b> FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X ± 1.0	.X° ±			
.XX ± 0.2	.XX° ±	FINISH	PART NO. (INTENDED USE) ASAA82*-E8SB0-*H	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
.XXX ±	.XXX° ±			TITLE: CUSTOMER DRAWING 260PIN SODDR4 8.0 STD.
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.			APPD: Bruce Wu	DWG NO.: 317-0000-2535
			CHKD: C.S Li	SCALE SHEET REV. N/A 6/6 B
Q'TY			DRAW: Brooks Yang 2016/3/16	

CONNECTOR P/N	ASAA82*-E8SB0-7H
---------------	------------------